

FM501V-FL-Q1

List

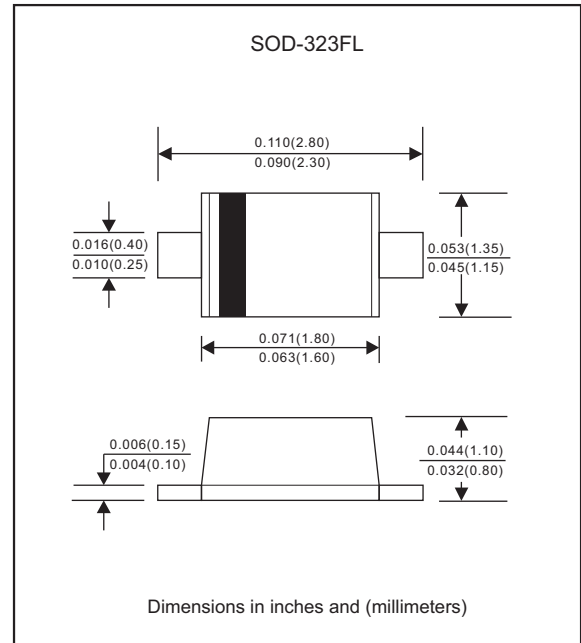
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FM501V-FL-Q1**100mA Surface Mount
Small Signal Schottky Diode- 40V****Features**

- Low Forward Voltage Drop
- Flat Lead SOD-323FL Small Outline Plastic Package
- Surface Device Type Mounting
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- Qualified to AEC-Q101 standards for high reliability.
- Suffix "-H" for Halogen-free part, ex. FM501V-FL-Q1-H.

Mechanical data

- Epoxy:UL94-VO rated flame retardant
- Case : Molded plastic, SOD-323FL
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.004 gram

Package outline**Maximum ratings** (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	Value	UNIT
Power Dissipation		P_D	200	mW
Repetitive Peak Reverse Voltage		V_{RRM}	40	V
Reverse Voltage		V_R	40	V
Forward Current		I_F	100	mA
Non-Repetitive Peak Forward Current	8.3mS Single Half-wave for 1cycle	I_{FSM}	1.0	A
Operating Junction Temperature		T_J	+125	$^{\circ}\text{C}$
Storage Temperature Range		T_{STG}	-55~+125	$^{\circ}\text{C}$

These ratings are limiting values above which the serviceability of the diode may be impaired.

Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Breakdown Voltage	$I_R = 500\mu\text{A}$	V_{BR}	40			V
Forward voltage	$I_F = 10\text{ mA}$ $I_F = 100\text{ mA}$	V_F			0.34 0.55	V
Reverse current	$V_R = 10\text{ V}$	I_R			30	μA
Capacitance Between Terminals	$V_R = 10\text{ V}$, $f = 1\text{ MHz}$	C_T		6		pF

Rating and characteristic curves (FM501V-FL-Q1)

Fig. 1 Forward characteristics

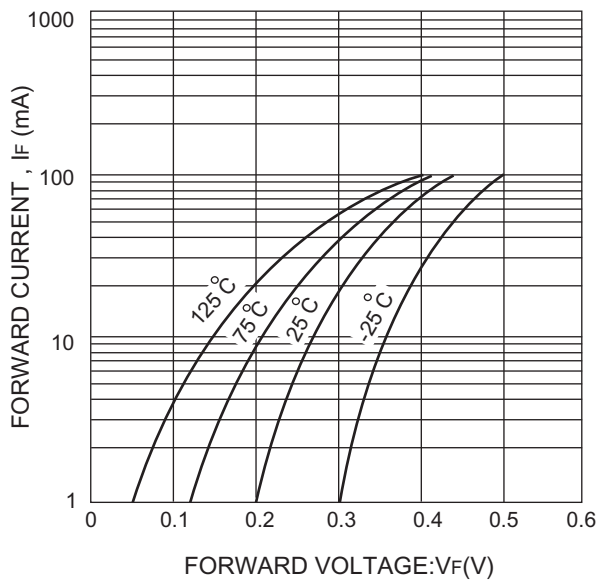


Fig.2 Reverse characteristics

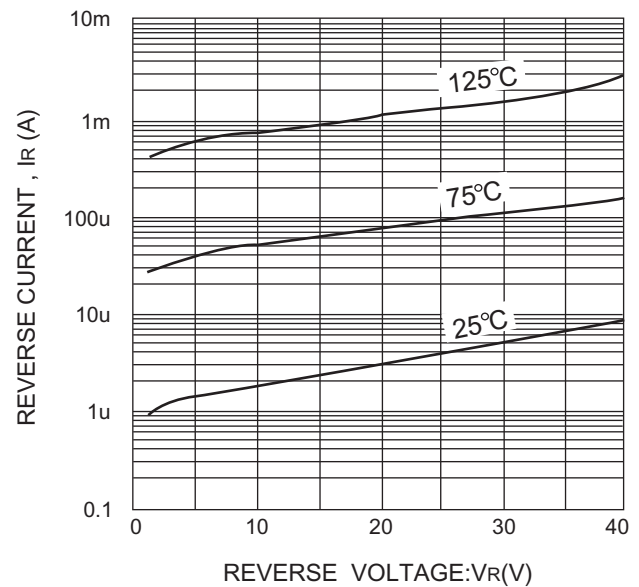


Fig. 4 Derating curve
(mounting on glass epoxy PCBs)

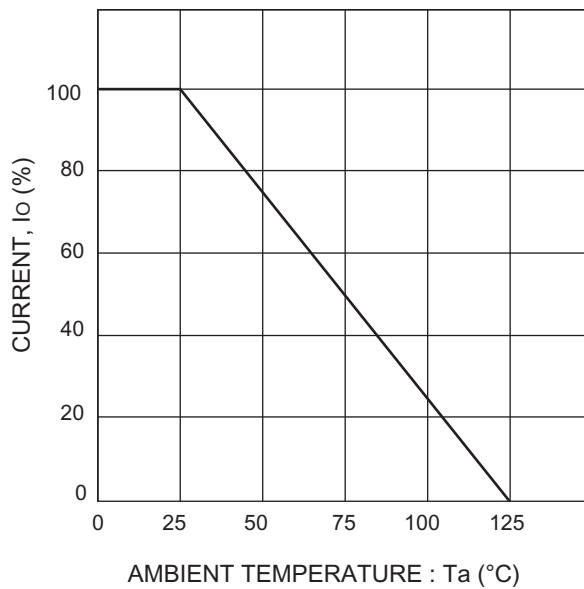
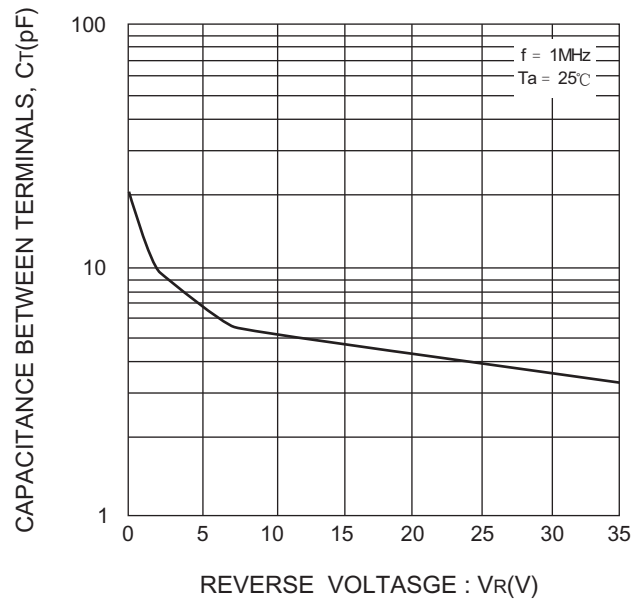
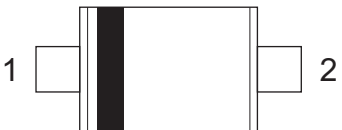


Fig.3 Capacitance between terminals characteristics

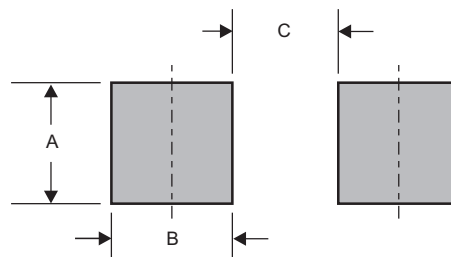


FM501V-FL-Q1**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
FM501V-FL-Q1	S7

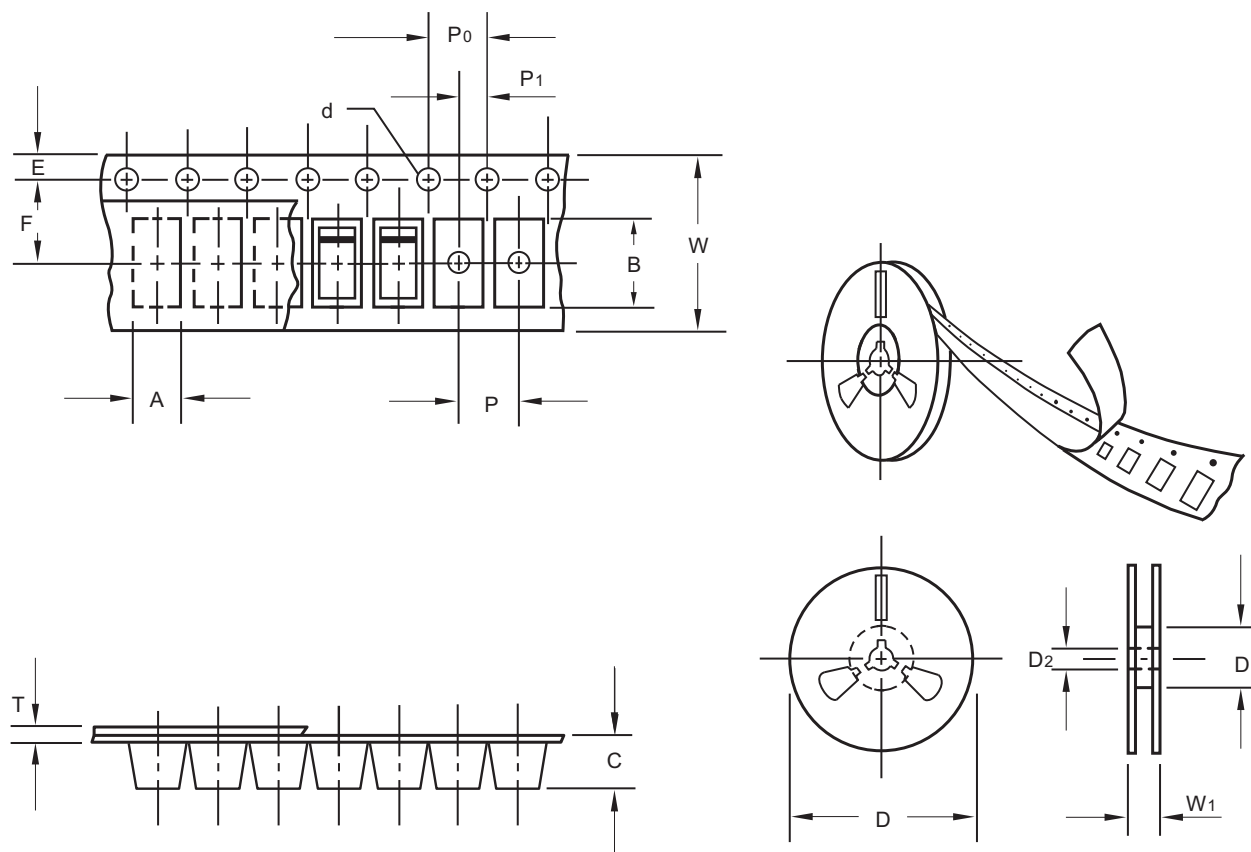
Suggested solder pad layout

Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323FL	0.032 (0.82)	0.022 (0.56)	0.069 (1.75)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323FL
Carrier width	A	0.1	1.46
Carrier length	B	0.1	2.95
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

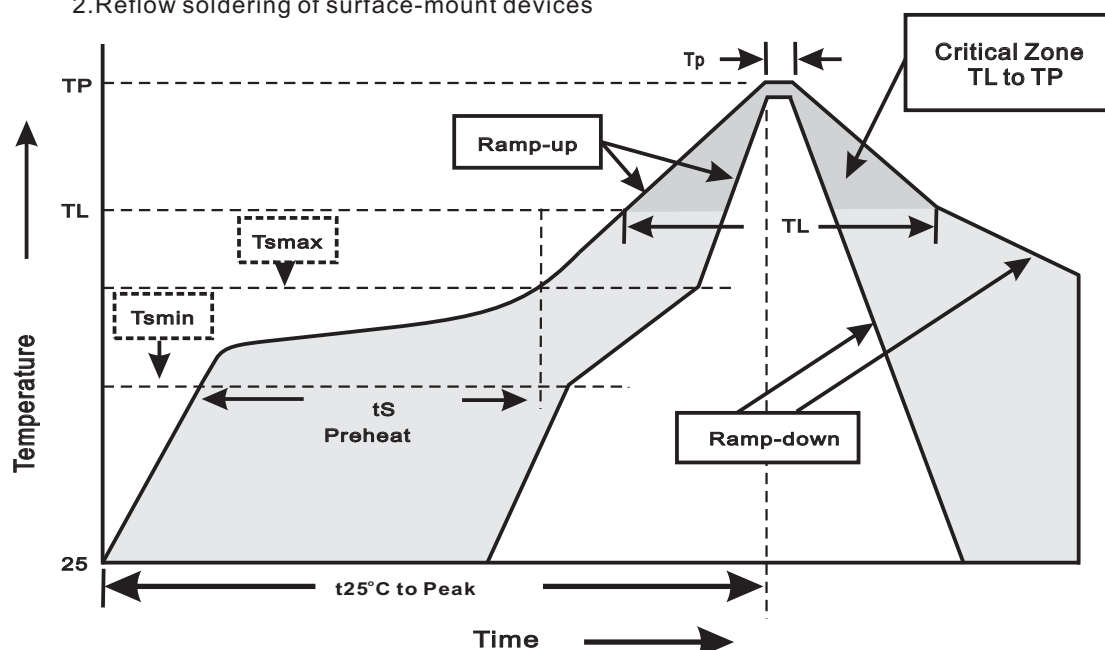
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323FL	7"	3,000	4.0	30,000	183*183*123	178	382*262*387	240,000	9.5

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. High Temperature Reverse Bias	$V_{BR}=V_{BR\ Nom}*80\%$ ($T_j=150^{\circ}C$)Test Duration:1000hrs	JESD22-A108
3. High Temperature Storage Life	$T_a=125^{\circ}C$ Test Duration: 1000hrs	JESD22 A-103
4. Temperature Cycle	$-55^{\circ}C$ (15min) to $150^{\circ}C$ (15min)Test Cycles: 1000cycles	JESD22 A-104
5. Autoclave	$P=2atm$ $T_a=121^{\circ}C$ RH=100% Test Duration:96hrs	JESD22 A-102
6. Solderability	$245\pm5^{\circ}C$ for 5sec	J-STD-002
7. Moisture Resistance	$T_a=85^{\circ}C$ /85% Relative humidity Test Duration:1000hrs	MIL-STD-750E METHOD 1021.2
8. Resistance To Solder Heat	$260\pm5^{\circ}C$ for 10sec	JESD22 B-106
9. High Temperature High Humidity Reverse Bias	$T_a=85^{\circ}C$, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration:1000hrs	JESD22-A101